

**IN THE CLAIMS**

1. (Original) A semiconductor device, comprising:  
square first semiconductor chip and square second  
semiconductor chip laminated with their respective one main  
surfaces opposite to each other;

a supporting lead a part of which is arranged between one  
main surface of the first semiconductor chip and one main  
surface of the second semiconductor chip; and

a resin sealing body that seals the first semiconductor  
chip, the second semiconductor chip and the supporting lead,  
wherein:

the respective one main surfaces of the first  
semiconductor chip and the second semiconductor chip are  
bonded to a part of the supporting lead via an adhesive layer;  
and

a part of the supporting lead is formed so that it has  
smaller width than the respective sides of the first  
semiconductor chip and the second semiconductor chip.

Claims 2-22 (Canceled)